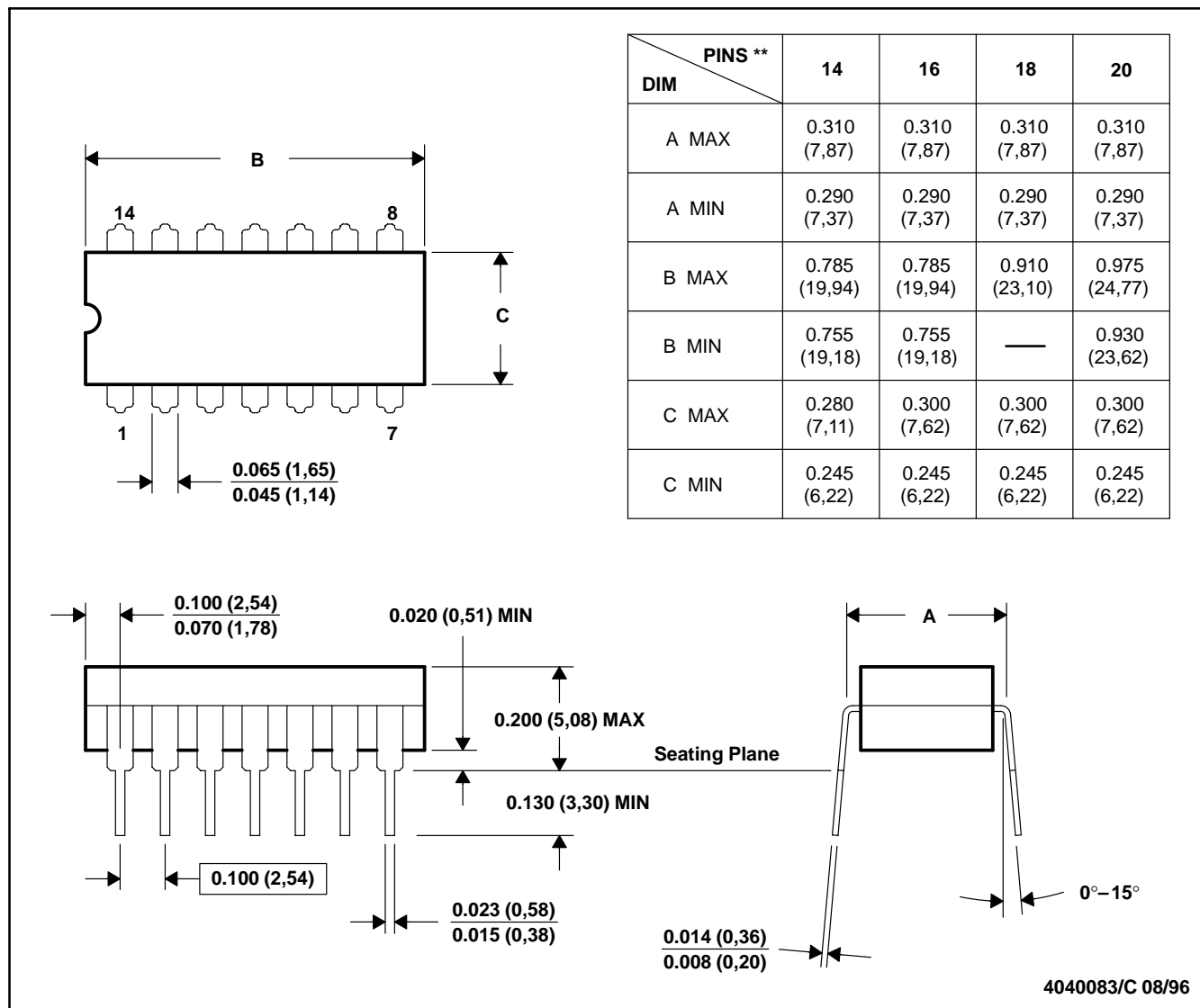


J (R-GDIP-T)****CERAMIC DUAL-IN-LINE PACKAGE**

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 E. Falls within MIL-STD-1835 GDIP1-T14, GDIP1-T16, GDIP1-T18, and GDIP1-T20

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